

ABSTRACT

There is provided a novel Al wiring material that achieves both of a suppression of chip damage and a thermal shock resistance. In aspect 1, the Al wiring material includes an Al core material and an Al coating layer formed on a surface of the Al core material, and satisfies $1.2 \leq H_{1h}/H_{1s}$ where H_{1h} is a Vickers hardness of the Al core material (Hv) and H_{1s} is a Vickers hardness of the Al coating layer (Hv). In aspect 2, the Al wiring material includes an Al core material and an Al coating layer formed on a surface of the Al core material, and satisfies $1.2 \leq H_{2h}/H_{2s}$ where H_{2s} is a Vickers hardness of the Al core material (Hv) and H_{2h} is a Vickers hardness of the Al coating layer (Hv).

FIG. 1